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 Members of the Texas Instruments Widebus™ Family Output Ports Hove Equivelent 22 O Series 	SN54LVTH162241 WD PACKAGE SN74LVTH162241 DGG, DGV, OR DL PACKAGE (TOP VIEW)
 Output Ports Have Equivalent 22-Ω Series Resistors, So No External Resistors Are Required 	10E [1 48] 20E 1Y1 [2 47] 1A1
 State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power 	1Y1 U 2 47 U 1A1 1Y2 [3 46] 1A2 GND [4 45] GND 1Y3 [5 44] 1A3
 Dissipation Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 	1Y4 [] 6 43 [] 1A4 V _{CC} [] 7 42 [] V _{CC} 2Y1 [] 8 41 [] 2A1
 3.3-V V_{CC}) Support Unregulated Battery Operation 	2Y2 0 9 40 0 2A2 GND 0 10 39 0 GND
 Down to 2.7 V High-Impedance State During Power Up and Power Down 	2Y3 [] 11 38 [] 2A3 2Y4 [] 12 37 [] 2A4 3Y1 [] 13 36 [] 3A1
 Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	3Y2 [] 14 35 [] 3A2 GND [] 15 34 [] GND 3Y3 [] 16 33 [] 3A3
 ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0) 	3Y4 [17 32] 3A4 V _{CC} [18 31] V _{CC} 4Y1 [19 30] 4A1
 Latch-Up Performance Exceeds 500 mA Per JESD 17 	4Y2 [20 29] 4A2 GND [21 28] GND
 Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors 	4Y3 [] 22 27]] 4A3 4Y4 [] 23 26]] 4A4 4OE [] 24 25]] 3OE

- Power Off Disables Inputs/Outputs, Permitting Live Insertion
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

These 16-bit buffers/drivers are designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. The devices provide noninverting outputs and complementary output-enable (OE and \overline{OE}) inputs.



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description (continued)

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 22-Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, OE should be tied to V_{CC} through a pullup resistor and OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54LVTH162241 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74LVTH162241 is characterized for operation from -40°C to 85°C.

FUNCTION TABLES									
INPU	OUTPUTS								
10E, 40E	1A, 4A	1Y, 4Y							
L	Н	Н							
L	L	L							
н	Х	Z							

FUNCTION TABLES

INPU	INPUTS					
20E, 30E	2A, 3A	2Y, 3Y				
Н	Н	Н				
н	L	L				
L	х	Z				



logic symbol[†]

					I	
1 <mark>0E</mark>	1	EN1				
20E	48	EN2				
30E	25	EN3				
4 <u>0</u> E	24	EN4				
40E				_		
1A1	47	┍┸──	1	1 🗸	2	1Y1
1A2	46	<u> </u>	•	• •	3	1Y2
1A2	44				5	1Y3
1A3	43				6	1Y4
2A1	41		1	2 ▽	8	2Y1
2A1 2A2	40		•	2 ∨	9	211 2Y2
2A2 2A3	38				11	212 2Y3
	37				12	
2A4	36	 	4	3 ▽	13	2Y4
3A1	35		1	3 V	14	3Y1
3A2	33				16	3Y2
3A3	32				17	3Y3
3A4	30				19	3Y4
4A1	29		1	4 ▽	20	4Y1
4A2	27				22	4Y2
4A3	26				23	4Y3
4A4						4Y4

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Current into any output in the low state, IO	30 mA
Current into any output in the high state, I _O (see Note 2)	30 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ_{JA} (see Note 3): DGG package	
DGV package	
DL package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$. 3. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 4)

			SN54LVTH	162241	SN74LVTH	UNIT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2	M.	2		V
VIL	Low-level input voltage		S 0.8		0.8	V	
VI	Input voltage		5.5		5.5	V	
ЮН	High-level output current		5	-12		-12	mA
IOL	Low-level output current		ng	12		12	mA
$\Delta t / \Delta v$	Input transition rise or fall rate	Outputs enabled	00	10		10	ns/V
$\Delta t / \Delta V_{CC}$	Power-up ramp rate		Q 200		200		μs/V
Т _А	Operating free-air temperature			125	-40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			LVTH16	2241	SN74				
					TYP†	MAX	MIN	TYP†	MAX	UNIT	
VIK		V _{CC} = 2.7 V,	l _l = –18 mA			-1.2			-1.2	V	
Vон		V _{CC} = 3 V,	I _{OH} = -12 mA	2			2			V	
VOL		V _{CC} = 3 V,	I _{OL} = 12 mA			0.8			0.8	V	
		V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			10			10		
1.	Control inputs	V _{CC} = 3.6 V,	$V_{I} = V_{CC} \text{ or } GND$			±1			±1	μΑ	
łı	Detainente	V _{CC} = 3.6 V	$V_I = V_{CC}$			1			1		
	Data inputs	VCC = 3.0 V	$V_{I} = 0$			-5			-5		
loff		$V_{CC} = 0,$	V_{I} or $V_{O} = 0$ to 4.5 V			_±100			±100	μA	
1.4	Data inputs	ata inputs V _{CC} = 3 V	V _I = 0.8 V	75	75 75 -75 2 -75					μA	
l(hold)			V _I = 2 V	-75						μ-	
IOZH		$V_{CC} = 3.6 \text{ V}, \qquad V_{O} = 3 \text{ V}$ 5				5	μA				
I _{OZL}		V _{CC} = 3.6 V,	$V_{O} = 0.5 V$		SC.	-5			-5	μΑ	
IOZPU‡	÷	$V_{CC} = 0$ to 1.5 V, $V_{O} = 0$ OE/OE = don't care	0.5 V to 3 V,	AOA	2	±100			±100	μA	
I _{OZPD} ‡	:	$V_{CC} = 1.5 V \text{ to } 0, V_{O} = 0$ OE/OE = don't care	0.5 V to 3 V,	~		±100			±100	μΑ	
			Outputs high			0.19			0.19		
ICC	$V_{CC} = 3.6 V, I_{O} = 0,$	$V_{CC} = 3.6 \text{ V}, \text{ IO} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		5				5	mA	
			Outputs disabled			0.19	0.19				
		V_{CC} = 3 V to 3.6 V, One Other inputs at V_{CC} or C				0.2			0.2	mA	
Ci		V _I = 3 V or 0			4			4		pF	
Co		V _O = 3 V or 0	$V_{O} = 3 V \text{ or } 0$		9			9		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. [‡] This parameter is warranted but not production tested.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

			S	N54LVT	H162241			SN74	LVTH16	2241							
PARAMETER	FROM (INPUT)	-	-	-	-	-	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	түр†	MAX	MIN	MAX						
^t PLH	A	Y	1.3	4.3	N	4.9	1.4	3	4.1		4.7	ns					
^t PHL		I	1.3	4.3	JIE I	4.9	1.4	2.4	4.1		4.7	115					
^t PZH	OE or OE	Y	1.1	5.2	RE	5.9	1.2	3.5	4.9		5.7	ns					
^t PZL	OE of OE	I	1.4	5	4	5.4	1.5	3.5	4.8		5.2	115					
^t PHZ	OE or OE	Y	1.9	5.5		6.2	2	3.7	5.3		5.9	ns					
^t PLZ		I.	1.9	5.2		5.7	2	3.6	4.9		5.4	115					
t _{sk(o)} ‡				2					0.5		0.5	ns					

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25° C.

[‡] Skew between any two outputs of the same package switching in the same direction. This parameter is warranted but not production tested.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CI includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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